

3696U-8  
10/076536  
02/19/02

U.S. UTILITY Patent Application

PATENT NUMBER and  
ISSUE DATE

APPL NUM 10076536	FILING DATE 02/19/2002	CLASS 255 127	SUBCLASS 291	GAU 1762	EXAMINER Wong
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1753

**\*\*CONTINUING DATA VERIFIED:**

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**\*\* FOREIGN APPLICATIONS VERIFIED:**  
JAPAN 2001-048685 02/23/2001

PG-PUB DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☐ no  
35 USC 119 conditions met ☐ yes ☐ no  
Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO

A8319.0014/P014

**TITLE :** Electroless copper plating solution, electroless copper plating process and production process of circuit board

U.S. DEPT. OF COMM./PAT. & TM.-PTO-425L(Rev. 12-94)

NOTICE OF ALLOWANCE MAILED

CLAIMS ALLOWED

Assistant Examiner

Total Claims

Print Claim for  
O.G

ISSUE FEE

Amount Due

Date Paid

DRAWING

Sheets Drwg.

Figs.Drwg.

Print Fig.

Primary Examiner

PREPARED FOR ISSUE

Application Examiner



TERMINAL

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